

New Patent Claims

1. A method for making contact between at least one module for wire-free radio standards and at least one application, with
- contact surfaces being provided on a side of the module which is intended to make contact with the application, and
 - contact surfaces which can interact with the contact surfaces of the module being provided on a side of the application which is intended to make contact with the module, with
 - the contact surfaces being formed by a metallic coating with a low electrical and/or thermal resistance and a connection being produced between the respective contact surfaces of the module and the application.
2. The method as claimed in claim 1, characterized in that a detachable connection is provided between the respective contact surfaces by means of a mechanical apparatus which allows the module to be replaced by pushing it in and out.
3. The method as claimed in claim 1, characterized in that a firm connection is provided between the respective contact surfaces.
4. The method as claimed in claim 3, characterized in that the respective contact surfaces are soldered or pressed together.

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5. The method as claimed in one of the preceding claims,
characterized
in that the respective contact surfaces are
5 arranged in the form of a grid.
6. A combination, having a module for wire-free radio standards and having an application, with the
10 module having contact surfaces on a side which is intended to make contact with the application, and the application having contact surfaces on a side which is intended to make contact with the module, which latter contact surfaces can interact with the contact surfaces of the module and can make
15 contact with them, with the contact surfaces being formed by a metallic coating with a low electrical and/or thermal resistance.
7. The combination as claimed in claim 6,
20 characterized
in that the respective contact surfaces can be detachably connected to one another.
8. The combination as claimed in claim 6,
25 characterized
in that the respective contact surfaces can be permanently connected to one another.
9. The combination as claimed in claim 8,
30 characterized
in that the respective contact surfaces can be soldered to one another.
10. The combination as claimed in one of claims 6 to
35 9,

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